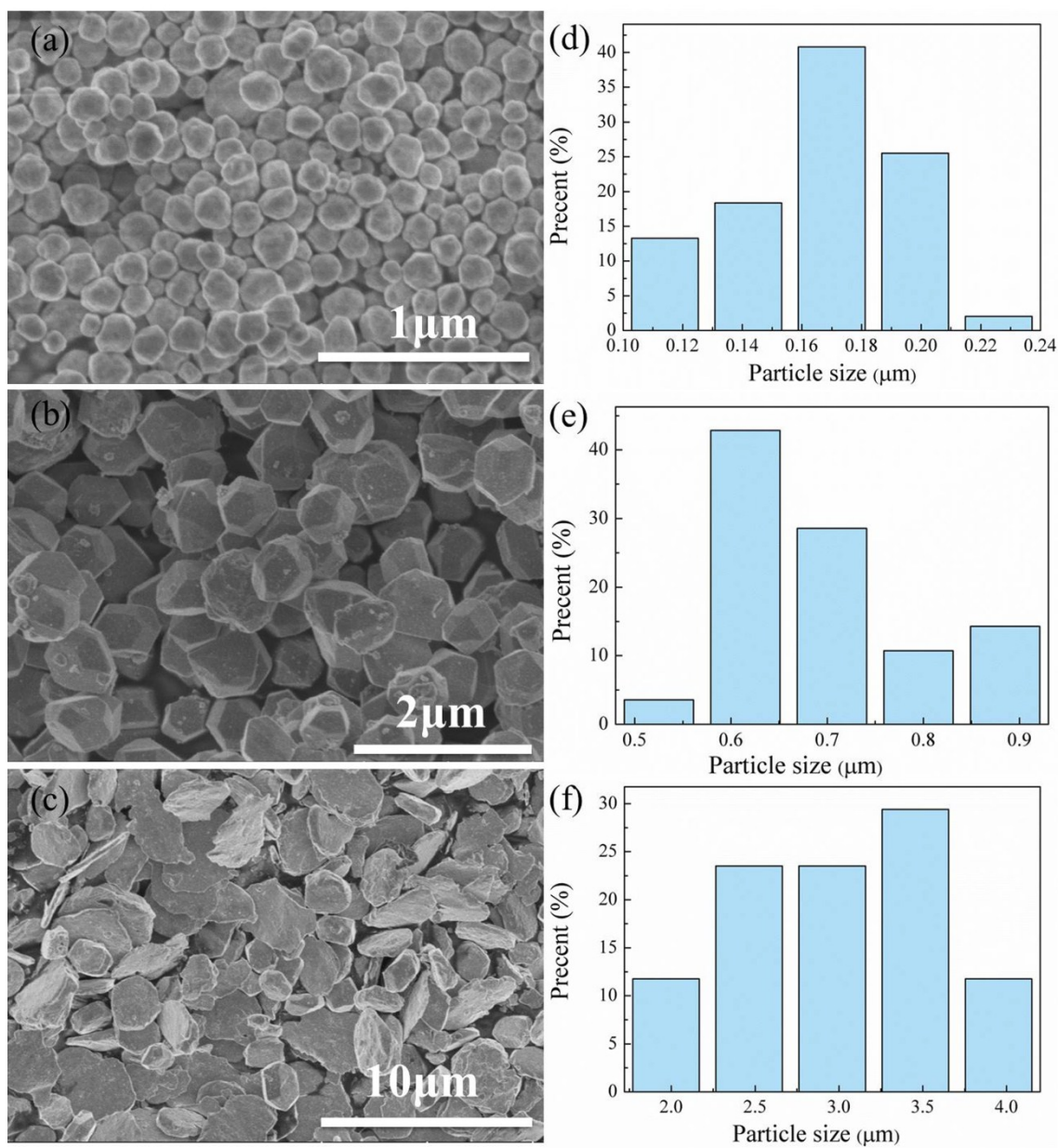


**Supporting information**

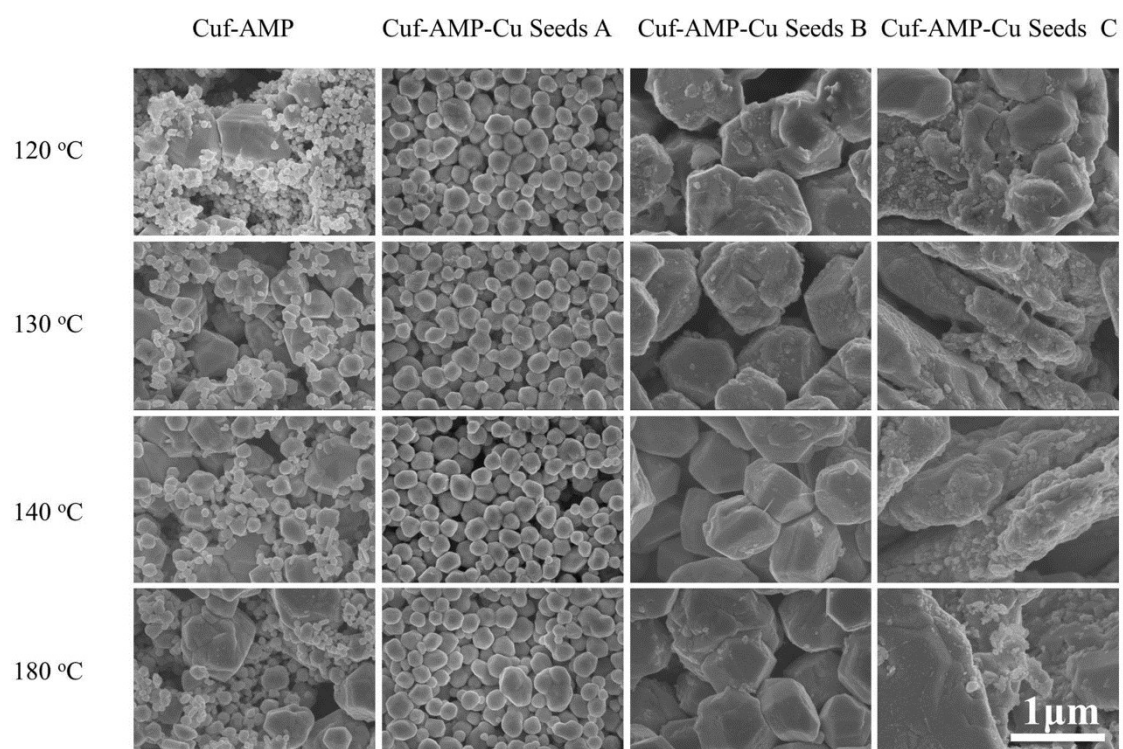
Low-temperature and self-reducible copper ink  
composed of copper-amino complexes and  
preset submicron copper seeds for high  
performance thick copper patterns on a  
flexible substrate

Wanli Li, Jinting Jiu, Shijo Nagao, and Katsuaki Suganuma

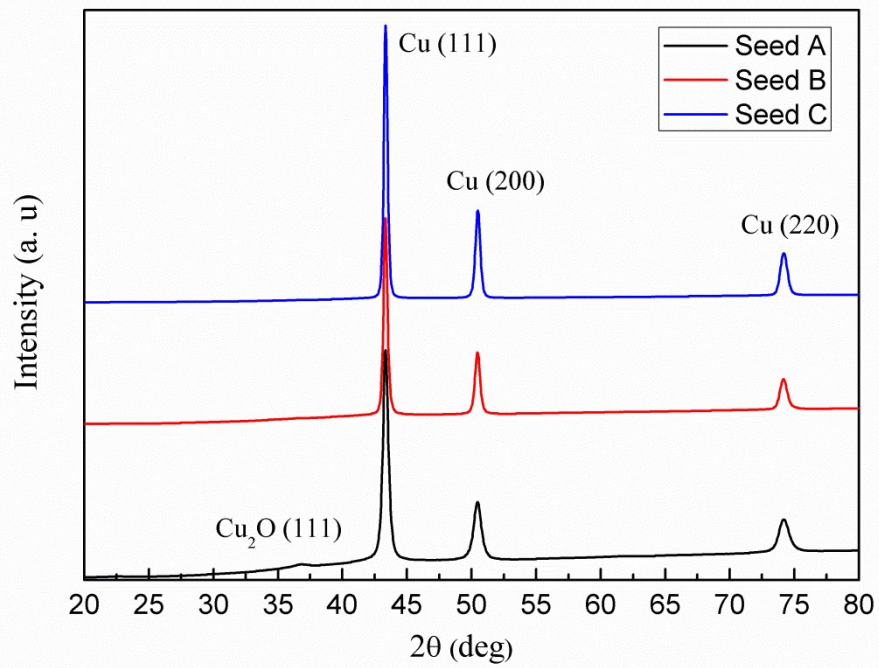
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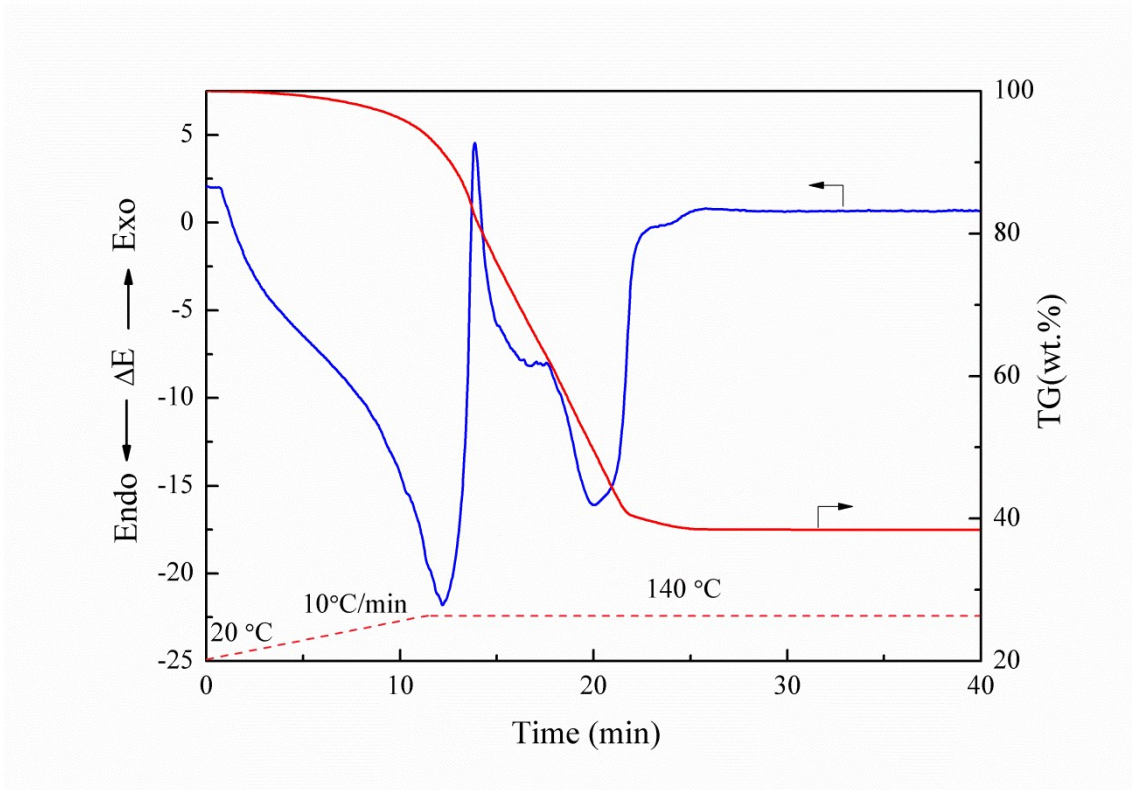
**Fig. S1** SEM micrographs of received copper particles (a) seeds A, (b) seeds B and (c) seeds C, and (d)-(f) are the corresponding particle size distribution.



**Fig. S2** Microstructure of sintered patterns after heat treatment at 120 °C, 130 °C, 140 °C and 180 °C under nitrogen atmosphere.



**Fig. S3** XRD patterns of seeds A, B and C.



**Fig. S4** Relative thermal decomposition analysis using TGA-DAT.